

September 2008

# FSQ500L Compact, Green Mode, Fairchild Power Switch (FPS™)

#### **Features**

- Single Chip 700V SenseFET Power Switch
- Precision Fixed Operating Frequency: 130kHz
- No-load consumption 250mW at 265V<sub>AC</sub> with Burst Mode and Down to 60mW with External Bias
- Internal Startup Switch
- Soft-Start Time Tuned by External Capacitor
- Under-Voltage Lockout (UVLO) with Hysteresis
- Pulse-by-Pulse Current Limit
- Overload Protection (OLP) and Internal Thermal Shutdown Function (TSD) with Hysteresis
- Auto-Restart Mode
- No Need for Auxiliary Bias Winding

### **Applications**

- Cost-Effective Linear Power Supplies Replacement
- Charger and Adapter for Mobile Phone, PDA, MP3, and Cordless Phone

## **Related Application Notes**

- AN-4137, AN-4141, AN-4147 (Flyback)
- AN-4138 (Charger)

### Description

The FSQ500L is specially designed for a replacement of linear power supplies with low cost. This device combines current-mode Pulse Width Modulator (PWM) with a senseFET. The integrated PWM controller features include: a fixed oscillator, Under Voltage Lockout (UVLO) protection, Overload Protection (OLP), Leading-Edge Blanking (LEB), an optimized gate turnon/turn-off driver, Thermal Shutdown (TSD) protection hysteresis. and temperature-compensated precision-current sources for loop compensation. When compared to a linear power supply, the FSQ500L device reduces total size and weight, while increasing efficiency, productivity, and system reliability. This device provides a basic platform for cost-effective flyback converters.



		_		
Maximum Output Power <sup>(1)</sup>				
230Vac	± 15% <sup>(2)</sup>	85-265V <sub>AC</sub>		
Adapter <sup>(3)</sup>	Open Frame <sup>(4)</sup>	Adapter <sup>(3)</sup>	Open Frame <sup>(4)</sup>	

2.0W

#### Notes:

2.5W

- The junction temperature can limit the maximum output power.
- 2. 230V<sub>AC</sub> or 100/115V<sub>AC</sub> with doubler.

3.0W

- Typical continuous power in a non-ventilated enclosed adapter measured at 50°C ambient.
- Maximum practical continuous power in an open frame design at 50°C ambient.

## Ordering Information

Part Number	Operating Temperature Range	<b>©</b> Eco Status	Package	Packing Method	
FSQ500L	-25°C to +85°C	RoHS	4-Lead, Small Outline Package (SOT223-4L)	Tape & Reel	

🖟 For Fairchild's definition of "green" Eco Status, please visit: <u>http://www.fairchildsemi.com/company/green/rohs\_green.html</u>.

2.5W

## **Application Circuit Diagram**

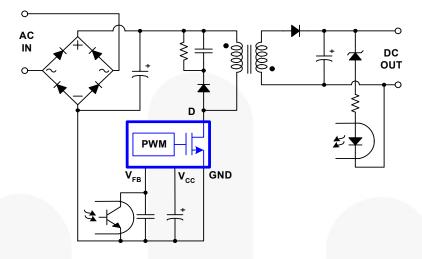


Figure 1. Typical Application Circuit

## **Internal Block Diagram**

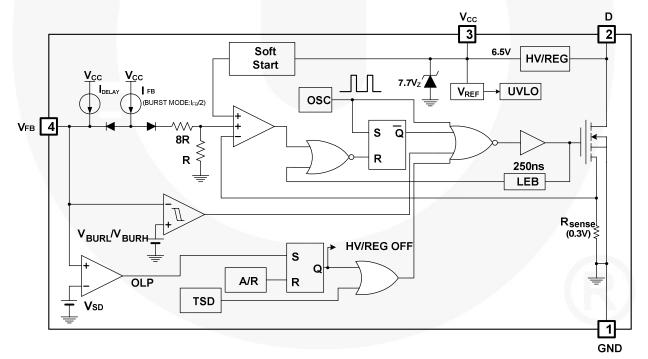


Figure 2. Internal Block Diagram

# **Pin Assignments**

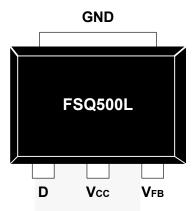


Figure 3. Package / Pin Diagram

## **Pin Definitions**

Pin#	Name	Description
1	GND	This pin is the control ground and the senseFET source.
2	D	High-voltage power senseFET drain connection. In addition, at startup, the internal high-voltage current source supplies internal bias and charges the external capacitor connected to the $V_{\rm CC}$ pin. Once $V_{\rm CC}$ reaches 6.0V, all internal blocks are activated. The internal high-voltage current source is alive until $V_{\rm CC}$ reaches 6.5V. After that, the internal high voltage current source turns on and off irregularly to maintain $V_{\rm CC}$ at 6.5V.
3	V <sub>CC</sub>	This pin is connected to a storage capacitor. A high-voltage regulator connected between pin 2 (D) and this pin provides the supply voltage to the FSQ500L at startup and when switching during normal operation. The FSQ500L eliminates the need for auxiliary bias winding and associated external components.
4	$V_{FB}$	This pin is internally connected to the non-inverting input of the PWM comparator. The collector of an opto-coupler is typically tied to this pin. For stable operation, a capacitor should be placed between this pin and GND. If the voltage of this pin reaches 4.5V, the overload protection triggers, which shuts down the FPS.

## **Absolute Maximum Ratings**

The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table defines the conditions for actual device operation.

Symbol	Parameter	Min.	Max.	Unit	
V <sub>DS</sub>	Drain Pin Voltage <sup>(5)</sup>	700		V	
V <sub>CC</sub>	Supply Voltage		10	V	
$V_{FB}$	Feedback Voltage Range	-0.3	$V_{CC}$	V	
$P_D$	Total Power Dissipation		0.78	W	
I <sub>DM</sub>	Drain Current Pulsed <sup>(6)</sup>		0.41	Α	
$T_J$	Operating Junction Temperature	-25	+150	°C	
T <sub>STG</sub>	Storage Temperature	-55	+150	°C	

#### Notes:

- 5. LDMOS available drain voltage is -0.3V ~ 700V.
- 6. Repetitive rating: pulse width is limited by maximum junction temperature.

## **Thermal Impedance**

Symbol	Parameter	Value	Unit	
$\theta_{JA}$	Junction-to-Ambient Thermal Resistance <sup>(7)</sup>	+160	°C/W	

#### Note

7. Free-standing with no heat sink; minimum land pattern.

### **Electrical Characteristics**

 $T_J = 25^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
SenseFE <sup>-</sup>	T Section					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{CC} = 6.5V$ , $V_{FB} = 0V$ , $I_D = 150\mu A$	700			V
I <sub>DSS</sub>	Zero-Gate-Voltage Drain Current	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> = 0V, V <sub>DS</sub> = 560V			150	μΑ
		T <sub>J</sub> = 25°C, I <sub>D</sub> = 25mA		25	29	Ω
$R_{DS(ON)}$	Drain-Source On-State Resistance	T <sub>J</sub> = 100°C, I <sub>D</sub> = 25mA		35	41	Ω
C <sub>ISS</sub>	Input Capacitance <sup>(8)</sup>	V <sub>GS</sub> = 6.5V		42		pF
Coss	Output Capacitance <sup>(8)</sup>	$V_{DS}$ = 40V, $f_S$ = 1MHz		25		pF
t <sub>r</sub>	Rise Time <sup>(8)</sup>	V <sub>DS</sub> = 350V, I <sub>D</sub> = 25mA		100		ns
t <sub>f</sub>	Fall Time <sup>(8)</sup>	V <sub>DS</sub> = 350V, I <sub>D</sub> = 25mA		50		ns
Control S	ection					•
fs	Switching Frequency	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> = 1.0V	120	130	140	kHz
$\Delta f_{S}$	Switching Frequency Variation <sup>(8)</sup>	-25°C < T <sub>J</sub> < 125°C		±5	±7	%
I <sub>FB(Burst)</sub>	Foodback Course Coursest	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> = 0V	98	110	122	μА
I <sub>FB(Normal)</sub>	Feedback Source Current	V <sub>CC</sub> = 6.5V	200	225	250	μΑ
D <sub>MAX</sub>	Maximum Duty Ratio	$V_{CC} = 6.5V, V_{FB} = 4.0V$	54	60	66	%
D <sub>MIN</sub>	Minimum Duty Ratio	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> = 0V			0	%
V <sub>START</sub>	LIVI O Throughold Voltage	V <sub>FB</sub> = 0V, V <sub>CC</sub> Sweep	5.5	6.0	6.5	V
V <sub>STOP</sub>	UVLO Threshold Voltage	After Turn-on, V <sub>FB</sub> = 0V, V <sub>CC</sub> Sweep	4.5	5.0	5.5	V
V <sub>DLY_EN</sub>	Shutdown Delay Current Enable Voltage	V <sub>FB</sub> = V <sub>SD</sub> , V <sub>CC</sub> Sweep from 6V	6.0	6.5	7.0	V
Burst-Mo	de Section					
$V_{\text{BURH}}$			0.75	0.80	0.85	V
$V_{BURL}$	Burst Mode Voltage	$V_{CC}$ = 6.5V, $V_{FB}$ Sweep	0.70	0.75	0.80	V
HYS			30	50	80	mV
Protectio	n Section					
I <sub>LIM</sub>	Peak Current Limit	di/dt = 150mA/μs	245	280	315	mA
$V_{SD}$	Shutdown Feedback Voltage	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> Sweep	4.1	4.5	4.9	V
I <sub>DELAY</sub>	Shutdown Delay Current	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> = 4.0V	4	5	6	μА
t <sub>LEB</sub>	Leading Edge Blanking Time <sup>(8)</sup>			250		ns
t <sub>CLD</sub>	Current Limit Delay Time <sup>(8)</sup>			100		ns
TDS	Thermal Shutdown Temperature <sup>(8)</sup>		130	140	150	°C
HYS	Thermal Shuldown Temperalure			80		°C
Total Dev	rice Section			•	V.	
I <sub>OP-BURST</sub>	Operating Supply Current (Control	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> = 0V	360	430	500	μА
I <sub>OP-FB</sub>	Part Only)	V <sub>CC</sub> = 6.5V, V <sub>FB</sub> = 4V	640	760	880	μΑ
I <sub>CH</sub>	Startup Charging Current	V <sub>CC</sub> = V <sub>FB</sub> = 0V, V <sub>DS</sub> = 40V	3.3			mA
V <sub>CCREG</sub>	Supply Shunt Regulator	V <sub>DS</sub> = 40V, V <sub>FB</sub> = 0V	6.0	6.5	7.0	V
V <sub>CCREG</sub> _	Supply Shunt Regulator During TSD <sup>(8)</sup>		5.2	5.7	6.2	V
	1	I.		1		<b></b>

#### Note:

8. These parameters, although guaranteed, are not 100% tested in production.

## **Typical Performance Characteristics**

These characteristic graphs are measured at  $T_A = 25$ °C.

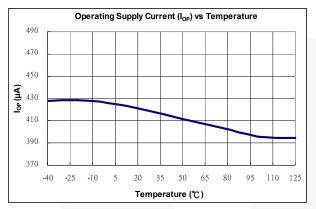


Figure 4. Operating Supply Current (I<sub>OP\_Burst</sub>) vs. Temperature

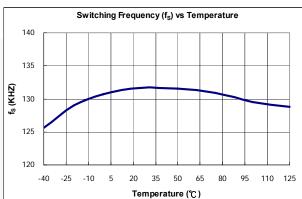


Figure 5. Switching Frequency (f<sub>s</sub>) vs. Temperature

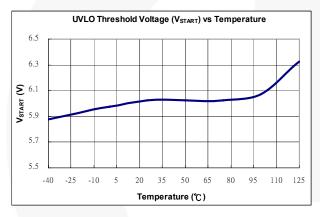


Figure 6. UVLO Threshold Voltage (V<sub>START</sub>) vs. Temperature

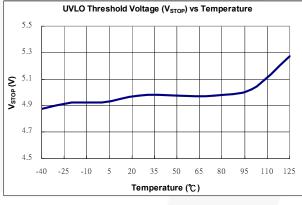


Figure 7. UVLO Threshold Voltage (V<sub>STOP</sub>) vs. Temperature

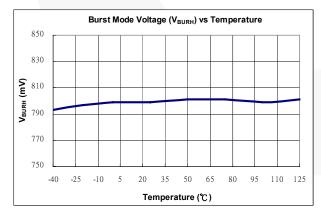


Figure 8. Burst-Mode Voltage (V<sub>BURH</sub>) vs. Temperature

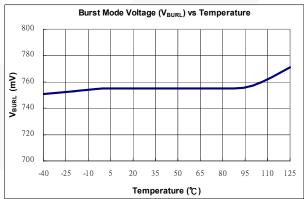
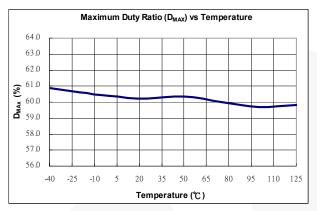


Figure 9. Burst-Mode Voltage (V<sub>BURL</sub>) vs. Temperature

## **Typical Performance Characteristics** (Continued)

These characteristic graphs are measured at  $T_A = 25$ °C.



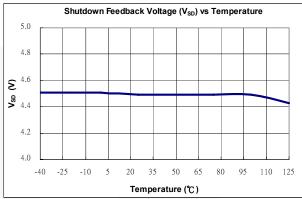
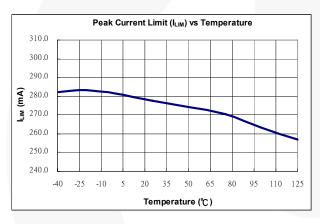


Figure 10.Maximum Duty Ratio (D<sub>MAX</sub>) vs. Temperature

Figure 11.Shutdown Feedback Voltage (V<sub>SD</sub>) vs. Temperature



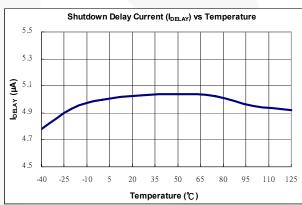


Figure 12.Peak Current Limit (I<sub>LIM</sub>) vs. Temperature

Figure 13. Shutdown Delay Current (I<sub>DELAY</sub>) vs. Temperature

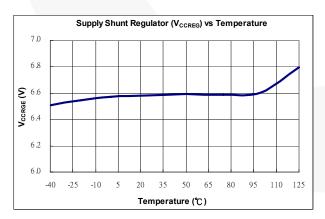


Figure 14. Supply Shunt Regulator (V<sub>CCREG</sub>) vs. Temperature

### **Functional Description**

1. Startup and  $V_{CC}$  Regulation: At startup, an internal high-voltage current source supplies the internal bias and charges the external capacitor ( $C_A$ ) connected to the  $V_{CC}$  pin, as illustrated in Figure 15. An internal high-voltage regulator (HV/REG) located between the D and  $V_{CC}$  pins regulates the  $V_{CC}$  to be 6.5V and supplies operating current. Therefore, FSQ500L needs no auxiliary bias winding.

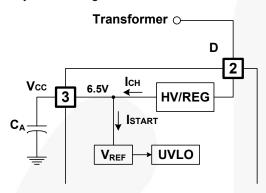


Figure 15. Startup Block

- 2. Feedback Control: FSQ500L employs current mode control, as shown in Figure 16. An opto-coupler (such as the FOD817A) and shunt regulator (such as the KA431) are typically used to implement the feedback network. Comparing the feedback voltage with the voltage across the  $R_{\text{sense}}$  resistor makes it possible to control the switching duty cycle. When the reference pin voltage of the regulator exceeds the internal reference voltage of 2.5V, the opto-coupler LED current increases, pulling down the feedback voltage and reducing the duty cycle. This typically happens when the line input voltage increases or the output load current decreases.
- 2.1 Pulse-by-Pulse Current Limit: Because current mode control is employed, the peak current through the senseFET is limited by the non-inverting input of PWM comparator ( $V_{FB}^*$ ), as shown in Figure 16. Assuming that 225µA current source flows only through the internal resistor (8R + R = 12k $\Omega$ ), the cathode voltage of diode D2 is about 2.7V. Since D1 is blocked when the feedback voltage ( $V_{FB}$ ) exceeds 2.7V, the maximum voltage of the cathode of D2 is clamped at this voltage, clamping  $V_{FB}^*$ . Therefore, the peak value of the current through the senseFET is limited.
- **2.2 Leading-Edge Blanking (LEB)**: At the instant the internal senseFET is turned on, a high-current spike occurs through the senseFET, caused by primary-side capacitance and secondary-side rectifier reverse recovery. Excessive voltage across the  $R_{\text{sense}}$  resistor would lead to incorrect feedback operation in the current mode PWM control. To counter this effect, the FPS employs a leading-edge blanking (LEB) circuit. This circuit inhibits the PWM comparator for a short time ( $t_{\text{LEB}}$  = 250ns) after the senseFET turns on.

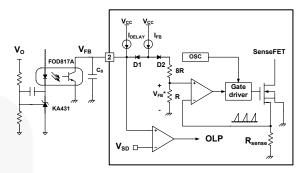


Figure 16. Pulse Width Modulation (PWM) Circuit

3. Protection Circuits: The FSQ500L has two selfprotective functions: overload protection (OLP) and thermal shutdown (TSD). While OLP is implemented as auto-restart mode, there is no switching when TSD triggers. Once the overload condition is detected, switching is terminated, the senseFET remains off, and HV/REG turns off. This causes  $V_{CC}$  to fall. When  $V_{CC}$ falls below the under voltage lockout (UVLO) stop voltage of 5.0V, the protection is reset and the startup circuit charges the V<sub>CC</sub> capacitor. When V<sub>CC</sub> reaches the start voltage of 6.0V, the FSQ500L resumes its normal operation. If the fault condition is still not removed, the senseFET and HV/REG remain off and V<sub>CC</sub> drops to V<sub>STOP</sub> again. In this manner, the autorestart can alternately enable and disable the switching of the power senseFET until the fault condition is eliminated, as shown in Figure 17.

Because these protection circuits are fully integrated into the IC without external components, reliability is improved without increasing cost.

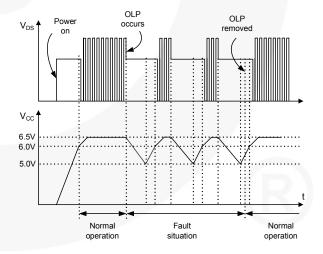
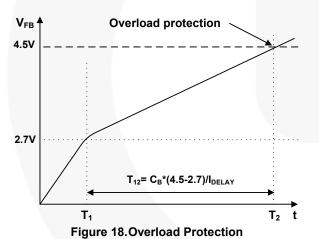


Figure 17. Auto Restart Protection Waveforms

3.1 Overload Protection (OLP): Overload is defined as the load current exceeding its normal level due to an unexpected abnormal event. In this situation, the protection circuit should trigger to protect the SMPS. However, even when the SMPS is in the normal operation, the overload protection circuit can be triggered during the load transition. To avoid this undesired operation, the overload protection circuit is designed to trigger after a specified time to determine whether the situation is transient or a true overload. Because of the pulse-by-pulse current limit capability, the maximum peak current through the senseFET is limited and, therefore, the maximum input power is restricted with a given input voltage. If the output consumes more than this maximum power, the output voltage (V<sub>O</sub>) decreases below the set voltage. This reduces the current through the opto-coupler LED, which also reduces the opto-coupler transistor current, thus increasing the feedback voltage ( $V_{\text{FB}}$ ). If  $V_{\text{FB}}$ exceeds 2.7V, D1 is blocked and the 5µA current source starts to charge CB slowly up to VCC. In this condition, VFB continues increasing until it reaches 4.5V, when the switching operation is terminated, as shown in Figure 18. The delay time for shutdown is the time required to charge  $C_B$  from 2.7V to 4.5V with 5 $\mu A$ . In general, a 10 ~ 50ms delay time is typical for most applications. This protection is implemented in auto restart mode.



3.2 Thermal Shutdown (TSD): The senseFET and the control IC in one package makes it easy for the control IC to detect an abnormal over temperature of the senseFET. When temperature the exceeds approximately 140°C, the thermal shutdown triggers. When TSD triggers, delay current is disabled, switching operation stops, and V<sub>CC</sub> through the internal highvoltage current source is set to 5.7V from 6.5V, as shown in Figure 19. Since TSD signal prohibits the senseFET from switching, there is no switching until the junction temperature decreases sufficiently. If the junction temperature is lower than 60°C typically, TSD signal is removed and V<sub>CC</sub> is set to 6.5V again. While V<sub>CC</sub> increases from 5.7V to 6.5V, the soft-start function makes the senseFET turn on and off with no voltage and/or current stress.

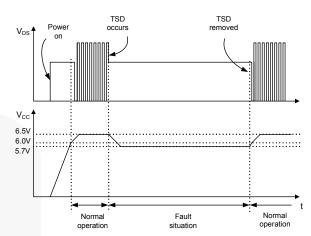


Figure 19. Over-Temperature Protection (OTP)

4. Soft-Start: The soft-start time is tuned by an external V<sub>CC</sub> capacitor (C<sub>A</sub>), which increases PWM comparator non-inverting input voltage together with the senseFET current slowly after it starts up. Before V<sub>CC</sub> reaches V<sub>START</sub>, C<sub>A</sub> is charged by the current I<sub>CH</sub>-I<sub>START</sub>, where I<sub>CH</sub> and I<sub>START</sub> are described in Figure 15. After V<sub>CC</sub> reaches V<sub>START</sub>, all internal blocks are activated, so that the current consuming inside IC becomes IOP. Therefore, CA is charged by the current ICH-IOP, which makes the increasing slope of  $V_{\text{CC}}$  become sluggish. V<sub>CC</sub> is shifted by 6.0V negatively (it is performed in softstart block in Figure 2), and then  $V_{\text{CC}}$  -6.0V is an input of one of the input terminals of the PWM comparator. The drain current follows V<sub>CC</sub> -6.0V instead of the V<sub>FB</sub>\* because of the low-dominant feature of the PWM comparator. The soft-start time can be made long or short by selecting C<sub>A</sub>, as described in Figure 20. During t<sub>S/S</sub>, I<sub>DELAY</sub> is disabled to avoid unwanted OLP. Typically,  $t_{S/S}$  is around 4.6ms with  $27\mu F$  of  $C_A$ .

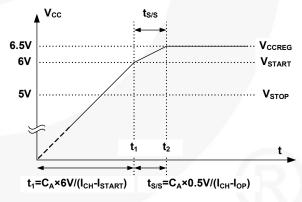


Figure 20. Soft-Start Function

The peak value of the drain current of the power switching device is progressively increased to establish the correct working conditions for transformers, inductors, and capacitors. The voltage on the output capacitors is progressively increased with the intention of smoothly establishing the required output voltage. It also helps to prevent transformer saturation and reduce stress on the secondary diode during startup.

**5. Burst Operation**: To minimize power dissipation in standby mode, the FPS enters burst-mode operation. During the burst mode operation,  $I_{FB(Burst)}$  decreases half of  $I_{FB(Normal)}$ . As the load decreases, the feedback voltage decreases. As shown in Figure 21, the device automatically enters burst mode when the feedback voltage drops below  $V_{BURL}$  (750mV). At this point, switching stops and the output voltages start to drop at a rate dependent on standby current load. This causes the feedback voltage to rise. Once it passes  $V_{BURH}$  (800mV), switching resumes. The feedback voltage then falls and the process repeats. Burst mode alternately enables and disables switching of the power senseFET, reducing switching loss in standby mode.

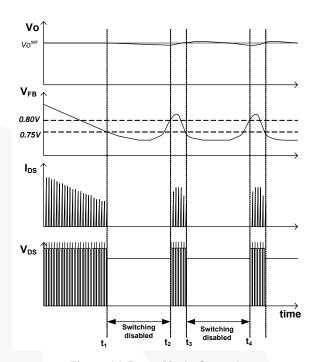


Figure 21.Burst-Mode Operation

## **Package Dimensions ⊕** 0.10 C B - 3.25 -1.90 6.10 1.90 0.84 2.30 2.30 0.95 4.60 **⊕** 0.10 CB LAND PATTERN RECOMMENDATION SEE DETAIL A -1.80 MAX △|0.08@|C 0.10 NOTES: UNLESS OTHERWISE SPECIFIED R0.15±0.05 -10° 5° DRAWING BASED ON JEDEC REGISTRATION TO-261, VARIATION AA. DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS. ALL DIMENSIONS ARE IN MILLIMETERS. GAGE R0.15±0.05 PLANE DRAWING CONFORMS TO ASME Y14.5M-1994. D) LANDPATTERN NAME: SOT230P700X180-4BN DRAWING FILENAME: MKT-MA04AREV2 0.25 10° 0.60 MIN SEATING 1.70 **PLANE** DETAIL A

Figure 22.4-Lead, Small Outline Package (SOT223-4L)

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- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS

#### Definition of Torms

Definition of Terms			
Datasheet Identification	Product Status	Definition	
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.	
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.	
No Identification Needed Full Production Datasheet contains final specifications. Fairchild Semiconductor reserves the ri at any time without notice to improve the design.		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.	
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.	

Rev. 136

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